

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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2SC3932G

Silicon NPN epitaxial planar type

For high-frequency amplification/oscillation/mixing

■ Features

- High transition frequency f_T
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

■ Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V_{CBO}	30	V	
Collector-emitter voltage (Base open)	V_{CEO}	20	V	
Emitter-base voltage (Collector open)	V _{EBO}	3	V	
Collector current	I_{C}	50	mA	
Collector power dissipation	P_{C}	150	mW	
Junction temperature	T _j	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

Package

- Code SMini3-F2
- Marking Symbol: R
- Pin Name
 - 1. Base
 - 2. Emitter
 - 3. Collector

■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

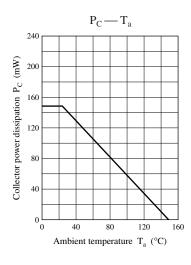
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = 100 \mu A, I_E = 0$	30	250		V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \mu\text{A}, I_C = 0$	3	, o		V
Base-emitter voltage	V_{BE}	$V_{CB} = 10 \text{ V}, I_{E} = -2 \text{ mA}$	1.90	720		mV
Forward current transfer ratio	h_{FE}	$V_{CB} = 10 \text{ V}, I_{E} = -2 \text{ mA}$	25		250	_
Transition frequency *	f_T	$V_{CB} = 10 \text{ V}, I_E = -15 \text{ mA}, f = 200 \text{ MHz}$	800		1 600	MHz
Reverse transfer capacitance (Common base)	C _{rb}	$V_{CE} = 6 \text{ V}, I_{C} = 0, f = 1 \text{ MHz}$		0.8		pF
Reverse transfer capacitance (Common emitter)	C _{re}	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 10.7 \text{ MHz}$		1.0	1.5	pF
Power gain	G_{P}	$V_{CB} = 10 \text{ V}, I_{E} = -1 \text{ mA}, f = 200 \text{ MHz}$		20		dB

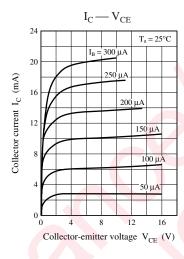
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

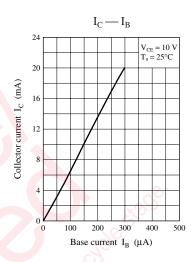
2. *: Rank classification

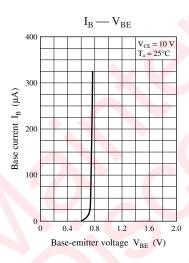
Rank	Т	S	No-rank
f_T	800 to 1400	1000 to 1600	800 to 1600
Marking symbol	RT	RS	R

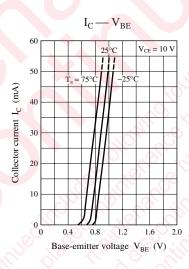
Product of no-rank is not classified and have no indication for rank.

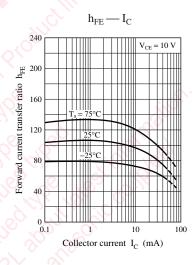


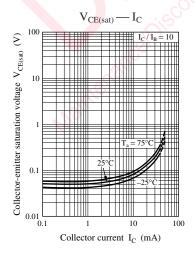


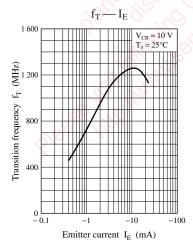


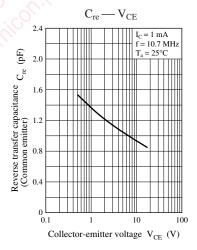




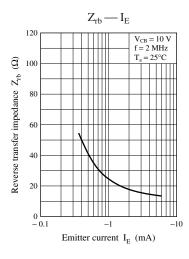


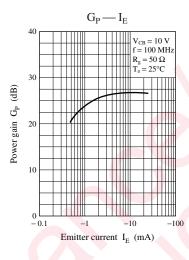


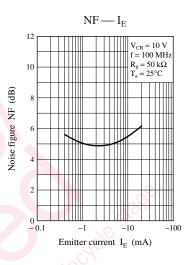


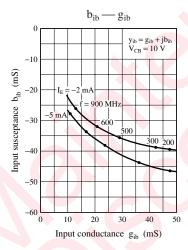


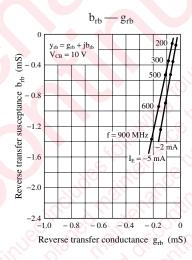
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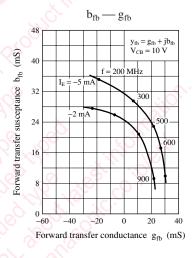


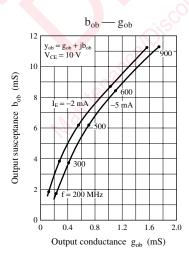




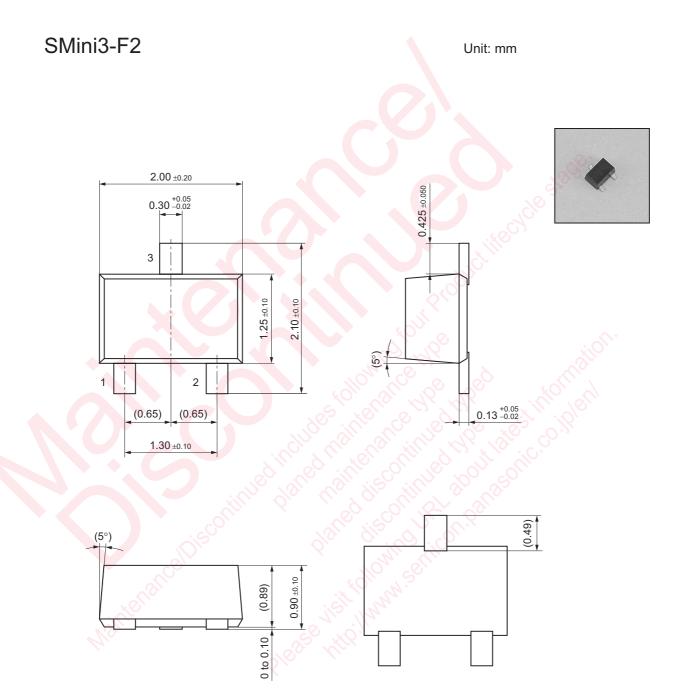








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